

**IN THE CLAIMS:**

No claims have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Previously Presented) A combination of a semiconductor substrate singulation saw and a chuck for holding a substrate comprising:

a saw having at least one blade supported above a table and oriented to cut mutually parallel

paths in a surface of a semiconductor substrate positioned on the table; and

a chuck having at least one cutting pedestal located thereon mounted on the table, the chuck for holding the substrate during cutting thereof by the saw.

2. (Previously Presented) The combination of claim 1, wherein the chuck further comprises:

a chuck table; and

a plurality of cutting pedestals, each cutting pedestal being mounted on the chuck table.

3. (Previously Presented) The combination of claim 2, wherein the chuck further comprises:

at least one clamp pedestal; and

at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.

4. (Previously Presented) The combination of claim 3, wherein the chuck further comprises:

at least one alignment apparatus having a portion attached to the chuck table.

5. (Previously Presented) The combination of claim 4, wherein the at least one alignment apparatus comprises:  
at least one alignment pin having a portion for engaging a portion of the substrate.

6. (Previously Presented) The combination of claim 4, wherein the at least one alignment apparatus comprises:  
an aperture in the chuck table for receiving the substrate therein.

7. (Previously Presented) The combination of claim 4, wherein the at least one alignment apparatus comprises:  
a pair of alignment pins, each alignment pin having a portion thereof attached to the chuck table  
and a portion thereof for engaging a portion of the substrate.

8. (Previously Presented) The combination of claim 1, wherein the saw further comprises:  
at least two blades for sawing the substrate.

9. (Previously Presented) The combination of claim 8, wherein at least one of the at least two blades is laterally translatable relative to another of the at least two blades.

10. (Previously Presented) The combination of claim 9, wherein the at least one of the at least two blades is raisable relative to the another of the at least two blades.

11. (Previously Presented) The combination of claim 8, wherein the table is translatable in at least one direction relative to the at least two blades.

12. (Previously Presented) The combination of claim 8, wherein the at least two blades are translatable in at least one direction relative to the table.

13. (Previously Presented) A combination of a semiconductor substrate singulation saw and a table for mounting a substrate comprising:  
a saw having at least two blades supported above a table and oriented to cut mutually parallel paths in a surface of a semiconductor substrate positioned on the table; and  
a chuck having at least one cutting pedestal located thereon mounted on the table, the chuck for holding the substrate during cutting thereof by the saw.

14. (Previously Presented) The combination of claim 13, wherein the chuck further comprises:  
a chuck table; and  
a plurality of cutting pedestals, each cutting pedestal being mounted on the chuck table.

15. (Previously Presented) The combination of claim 14, wherein the chuck further comprises:  
at least one clamp pedestal; and  
at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.

16. (Previously Presented) The combination of claim 15, wherein the chuck further comprises:  
at least one alignment apparatus having a portion thereof attached to the chuck table.

17. (Previously Presented) The combination of claim 16, wherein the at least one alignment apparatus comprises:  
at least one alignment pin having a portion for engaging a portion of the substrate.

18. (Previously Presented) The combination of claim 16, wherein the at least one alignment apparatus comprises:  
an aperture in the chuck table for receiving the substrate therein.

19. (Previously Presented) The combination of claim 16, wherein the at least one alignment apparatus comprises:  
a pair of alignment pins, each alignment pin having a portion thereof attached to the chuck table and a portion thereof for engaging a portion of the substrate.

20. (Previously Presented) The combination of claim 13, wherein the saw further comprises:  
at least two blades for sawing the substrate.

21. (Previously Presented) The combination of claim 20, wherein at least one of the at least two blades is laterally translatable relative to another of the at least two blades.

22. (Previously Presented) The combination of claim 21, wherein the at least one of the at least two blades is raisable relative to the another of the at least two blades.

23. (Previously Presented) The combination of claim 20, wherein the table is translatable in at least one direction relative to the at least two blades.

24. (Previously Presented) The combination of claim 20, wherein the at least two blades are translatable in at least one direction relative to the table.

25. (Previously Presented) A chuck used in semiconductor substrate singulation for holding a substrate to be singulated by a saw having a table comprising:  
a chuck having at least one cutting pedestal located thereon mounted on the table, the chuck for holding the substrate during cutting thereof by the saw.

26. (Previously Presented) The chuck of claim 25, further comprising:  
a plurality of cutting pedestals, each cutting pedestal being mounted on the table.

27. (Previously Presented) The chuck of claim 26, further comprising:  
at least one clamp pedestal; and  
at least one substrate clamp removably attached to a portion of the at least one clamp pedestal.

28. (Previously Presented) The chuck of claim 27, further comprising:  
at least one alignment apparatus having a portion attached to the table.

29. (Previously Presented) The chuck of claim 28, wherein the at least one alignment apparatus comprises:  
at least one alignment pin having a portion for engaging a portion of the substrate.

30. (Previously Presented) The chuck of claim 28, wherein the at least one alignment apparatus comprises:  
an aperture in the table for receiving the substrate therein.

31. (Previously Presented) The chuck of claim 28, wherein the at least one alignment apparatus comprises:  
a pair of alignment pins, each alignment pin having a portion thereof attached to the table and a portion thereof for engaging a portion of the substrate.